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HORIUCHI(10) **Pub. No.: US 2022/0361333 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **ELECTRONIC ELEMENT MOUNTING
SUBSTRATE, ELECTRONIC DEVICE, AND
ELECTRONIC MODULE**(52) **U.S. Cl.**CPC *H05K 1/116* (2013.01); *H05K 1/0298*
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Kyoto (JP)(21) Appl. No.: **17/613,514**(22) PCT Filed: **May 28, 2020**(86) PCT No.: **PCT/JP2020/021181**

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An electronic element mounting substrate includes a substrate including a first layer, a second layer located on a lower surface of the first layer, and a third layer located on a lower surface of the second layer, and on which an electronic element is to be mounted. The substrate has a via conductor that passes through the first layer to the third layer in a vertical direction. The substrate includes respective electrical conductor layers located between the respective layers and connected to the via conductor in a plan perspective. Each electrical conductor layer includes a land portion surrounding the via conductor, a clearance portion surrounding the land portion, and a peripheral portion surrounding the clearance portion and electrically insulated from the land portion with the clearance portion interposed between the land portion and the peripheral portion. The first land portion has, in a plan perspective, a first portion overlapping the second land portion, and the first clearance portion has, in a plan perspective, a second portion not overlapping the second clearance portion. The first peripheral portion and the second peripheral portion each have, in a vertical cross-sectional view, an end portion that becomes thinner as a distance from the via conductor increases.

